



Product Change Notification / JAON-18YCSW720

Date:

24-May-2022

Product Category:

Broadband Gateway

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5014.003 Initial Notice: Qualification of a new die size (1.932x1.860mm) for Die #1 of selected Microsemi LE9653AQC, LE9653AQCT, LE9621AQC, LE9643AQC, LE9621AQCT, and LE9643AQCT catalog part numbers (CPN) available in 36L VQFN (4x6x1mm) package assembled at ASEM assembly site.

Affected CPNs:

[JAON-18YCSW720_Affected_CPN_05242022.pdf](#)

[JAON-18YCSW720_Affected_CPN_05242022.csv](#)

Notification Text:

PCN Status:Initial Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of a new die size (1.932x1.860mm) for Die #1 of selected Microsemi LE9653AQC, LE9653AQCT, LE9621AQC, LE9643AQC, LE9621AQCT, and LE9643AQCT catalog part numbers (CPN) available in 36L VQFN (4x6x1mm) package assembled at ASEM assembly site.

Pre and Post Change Summary:

		Pre Change		Post Change	
Fabrication Location	Die # 1	Global Foundries, Singapore - Fab 7 (GF07)		Global Foundries, Singapore - Fab 7 (GF07)	
	Die # 2	Global Foundries, Singapore - Fab 2 (GF02)	Microchip Technology Colorado – Fab 5 (MCSO)	Global Foundries, Singapore - Fab 2 (GF02)	Microchip Technology Colorado – Fab 5 (MCSO)
Die Size	Die # 1	2.204 x 2.258 mm		1.932x1.860mm	
		Please see attached pre and post change comparison for Die # 1 Location			
	Die # 2	1.57 x 1.72 mm		1.57 x 1.72 mm	
Assembly Site		ASE Group -Malaysia (ASEM)		ASE Group -Malaysia (ASEM)	
Wire Material		CuPdAu		CuPdAu	
Die Attach Material		CRM1076DS		CRM1076DS	
Molding Compound Material		CEL-9240HF10AK-G1		CEL-9240HF10AK-G1	
Lead Frame Material		C194FH		C194FH	

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve productivity by qualifying a new die size.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:June 2022

Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	May 2022	June 2022
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Workweek	1 9	2 0	2 1	2 2	2 3	2 4	2 5	2 6	2 7
Initial PCN Issue Date				X					
Qual Report Availability							X		
Final PCN Issue Date							X		

Method to Identify Change:Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:May 24, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-18YCSW720_Pre and Post Change_Summary.pdf](#)
[PCN_JAON-18YCSW720_Qual_Plan.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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